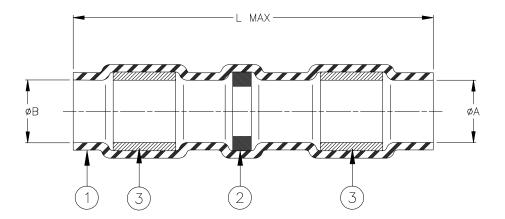
CUSTOMER DRAWING



Product	Pr	oduct Dimensio	ons	Solder Weight	Recovered I.D.	CMA
Name	L	øΑ	øΒ	Milligrams	max	Range*
	max	min	min			
D-144-41	26.8	1.9	2.4	42±6	1.27	600 - 1600
	(1.055)	(0.075)	(0.095)		(0.050)	
D-144-47	26.8	3.8	4.5	118±16	2.16	2800 - 4000
	(1.055)	(0.150)	(0.177)		(0.085)	
D-144-48	26.8	3.8	4.5	176±24	2.16	3800 - 7500
	(1.055)	(0.150)	(0.177)		(0.085)	

^{*} Not all combinations of wires equalling listed CMA's will fit in sleeve.

A and B dimensions are measured through the sealing ring closest to that end.

MATERIALS

- 1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked polyvinylidene fluoride.
- 2. SOLDER PREFORM WITH FLUX: (see table for weights)

SOLDER: TYPE Sn63 per ANSI J-STD-006.

FLUX: TYPE ROL0 per ANSI J-STD-004.

3. MELTABLE RINGS: Fluorocarbon-based thermoplastic. Color: gray.

APPLICATION

- 1. These parts are designed for use in making in-line splices in wires having tin or silver plated conductors and insulations rated for 135°C minimum, meeting the dimensional criteria listed. See table for applicable size ranges.
- 2. Parts are designed for installation with TE Connectivity-approved infrared heaters. They may also be installed with convection heaters equipped with the correct reflector. The use of a holding fixture will aid in holding the assembly alignment when heating sleeve.
- 3. Parts will provide environmental protection on splices having no more than 2 wires per side.
- 4. For ease of inspection, it is recommended that the splice contain no more than 4 wires.
- 5. All wires are to be stripped 12.7±1.27 (.50±.05) and overlapped under solder preform.

= TE				<i>Raychem</i> HERMOFIT DEVICES	SOLDERSLEEVE* SPLICE			
Unless otherwise specified dimensions are in millimeters. [Inches dimensions are shown in brackets]				D-144-41/-47/-48				
TOLERANCES:	ANGLES: N/A TE Connect		ctivity reserves the right to					
0.00 N/A 0.0 N/A 0 N/A	ROUGHN MICRON		amend this drawing at any time. Users should evaluate the suitability of the product for their application.		REV:	2	DATE: 09-Mar-2020	
DRAWN BY: M. FORON	IDA	DATE: 27-Sep	ot-2000	ECO: ECO-20-003687	SCALE:	ΓS	SIZE: A	SHEET: 1 of 1

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